

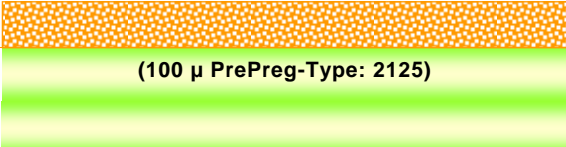
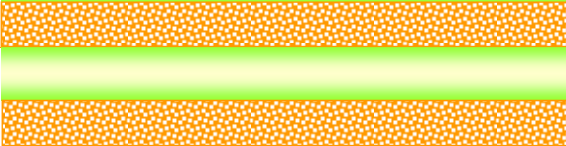
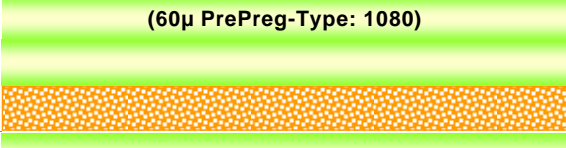

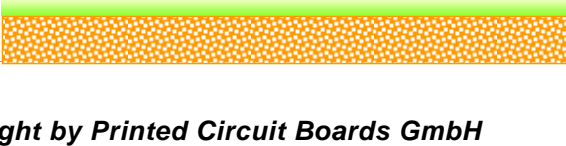
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 085 FR4 35 L10.35 P10_06 S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_085_FR4_35_L10.35_p10_06_s1

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper	 <p>(100 μ PrePreg-Type: 2125)</p>	A1
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-2	35 μ	Copper	 <p>(60μ PrePreg-Type: 1080)</p>	A2
	100 μ	L-FR4		
Layer-3	35 μ	Copper		
	60 μ	Prepreg	 <p>(60μ PrePreg-Type: 1080)</p>	B
Layer-4	35 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg	 <p>(60μ PrePreg-Type: 1080)</p>	A2
Layer-5	35 μ	Copper		
	60 μ	Prepreg		
	60 μ	Prepreg	 <p>(60μ PrePreg-Type: 1080)</p>	A2
Layer-99	35 μ	Copper		
	60 μ	Prepreg		

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